

## **Plasma Asher working instructions**

- **Machine applications**
- **Operation instructions**

## **Machine applications**

- **Cleaning**

Cleaning substrates e.g., wafers before lithography process.

The machine removes any organic material.

- **Activation of surfaces**

Surface activation helps with gluing low energy surfaces

- **Etching of surfaces**

(e.g. micro-structuring of silicon or etching of PR)

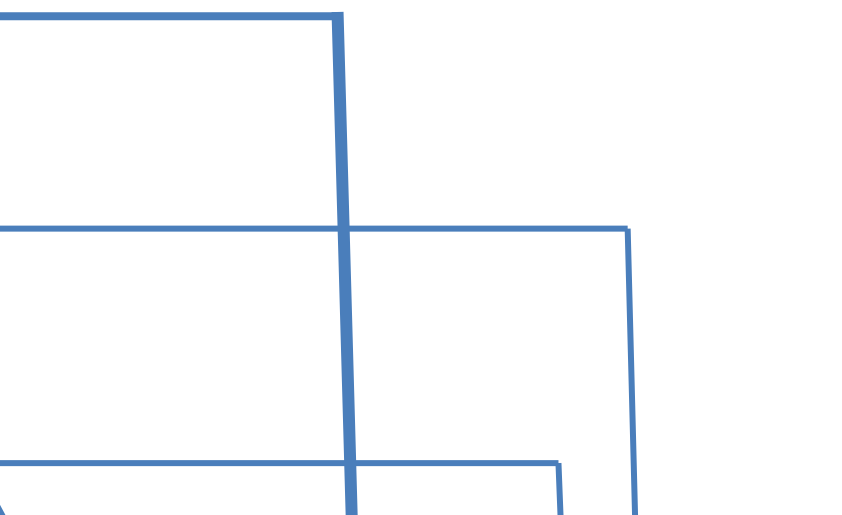

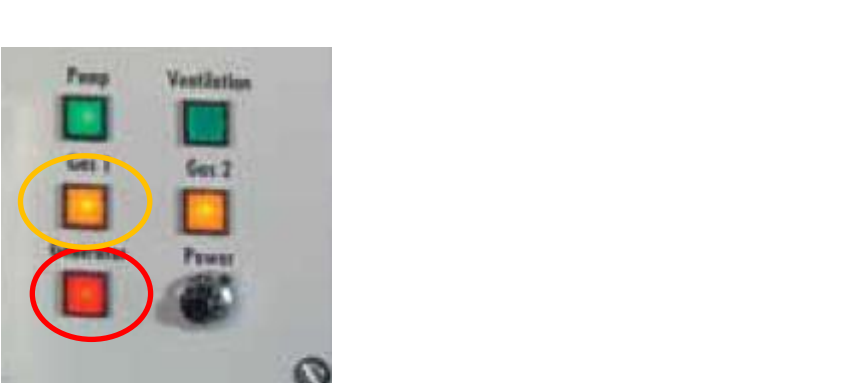
- **Coating of surfaces**

Plasma polymerization

(e.g. deposition of hydrophobic / hydrophilic layers)

## Operation instructions

- Verify the O<sub>2</sub> gas is open (in the chase).

<p>Press the on/off switch</p> <p>Press "Ventilation" To open the chamber. Hold the cover.</p>	
<p>Press "PUMP"</p> <p>Wait until the time display is on.</p> <p>Adjust the time: Sec., min., hours</p>	
<p>Press "Gas 1"</p> <p>Wait few seconds and press "Generator"</p>	

When the time display is darkened, press “Gas 1”; *Pump* and “Ventilation”.

Take the substrate out, press “*Pump*” for few seconds.

Turn the machine off.



- Prepare your substrates before you open the chamber.  
Or, close the chamber while placing the substrates on the plate.

**For any inquire call Avraham 052 2291 270**